

Features

- Fast Switching Speed
- Small Surface Mount Package •
- For General Purpose Switching Applications
- **High Conductance**
- Lead Free/RoHS Compliant (Note 1)
- "Green" Device (Notes 2 and 3)

Mechanical Data

- Case: SOT-26
- Case Material: Molded Plastic, "Green" Molding Compound, • Note 5. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Copper leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 Orientation: See Diagram
- Weight: 0.016 grams (approximate)



Top View



Top View Internal Schematic

Ordering Information (Notes 3 & 4)

| Part Number | Case | Packaging |
|-----------------|--------|------------------|
| MMBD4448HTM-7-F | SOT-26 | 3000/Tape & Reel |

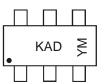
1. No purposefully added lead. Notes:

2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com.

Product manufactured with Date Code 0627 (week 27, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0627 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants

4. For packaging details, go to our website at http://www.diodes.com.

Marking Information



KAD = Product Type Marking Code YM = Date Code Marking Y =Year (ex: T = 2006) M = Month (ex: 9 = September)

| Date | Code | Kev |
|------|------|------|
| Dale | COUE | I/EV |

| Year | 2002 | 2003 | 2004 | 2005 | 2006 | 2007 | 2008 | 2009 | 2010 | 2011 | 2012 | 2013 | 2014 | 2015 |
|-------|------|------|------|------|------|------|------|------|------|------|------|------|------|------|
| Code | Ν | Р | R | s | Т | U | V | W | Х | Y | Z | А | В | С |
| Month | Jan | Feb | Ma | ar | Apr | May | Jun | Jul | Aug | Se | p (| Oct | Nov | Dec |
| Code | 1 | 2 | 3 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | | 0 | Ν | D |



Maximum Ratings @T_A = 25°C unless otherwise specified

| Characteristic | | Symbol | Value | Unit | |
|--|---------------------------|--|------------|------|--|
| Non-Repetitive Peak Reverse Voltage | | V _{RM} | 100 | V | |
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | | V _{RRM} V _{RWM} V _R | 80 | V | |
| RMS Reverse Voltage | | V _{R(RMS)} | 57 | V | |
| Forward Continuous Current (Note 5) | | I _{FM} | 500 | mA | |
| Average Rectified Output Current (Note 5) | | lo | 250 | mA | |
| Non-Repetitive Peak Forward Surge Current | @ t = 1.0μs @ t = 1.0s | I _{FSM} | 4.0 1.0 | A | |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|---|-----------------------------------|-------------|------|
| Power Dissipation (Note 5) | PD | 350 | mW |
| Thermal Resistance Junction to Ambient Air (Note 5) | $R_{	ext{	heta}JA}$ | 357 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -65 to +150 | ۵° |

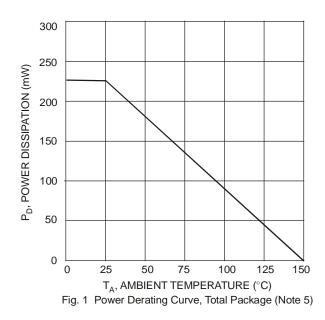
Electrical Characteristics $@T_A = 25^{\circ}C$ unless otherwise specified

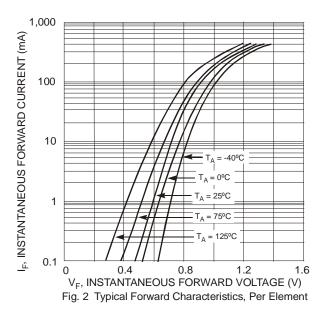
| Characteristic | Symbol | Min | Max | Unit | Test Condition |
|------------------------------------|--------------------|------|-------|------|--|
| Reverse Breakdown Voltage (Note 6) | V _{(BR)R} | 80 | _ | V | I _R = 2.5μA |
| | | 0.62 | 0.72 | | I _F = 5.0mA |
| Forward Voltage | VF | _ | 0.855 | V | $I_F = 10 \text{mA}$ |
| Folward voltage | VF | | 1.0 | v | I _F = 100mA |
| | | _ | 1.25 | | I _F = 150mA |
| | | | 100 | nA | V _R = 70V |
| Poweree Current (Note 6) | | 1 | 50 | μΑ | V _R = 75V, T _J = 150°C |
| Reverse Current (Note 6) | I _R | _ | 30 | μA | V _R = 25V, T _J = 150°C |
| | | | 25 | nA | $V_R = 20V$ |
| Total Capacitance | CT | | 3.5 | pF | V _R = 6, f = 1.0MHz |
| Reverse Recovery Time | t _{rr} | _ | 4.0 | ns | $V_{R} = 6V, I_{F} = 5mA$ |

Notes:

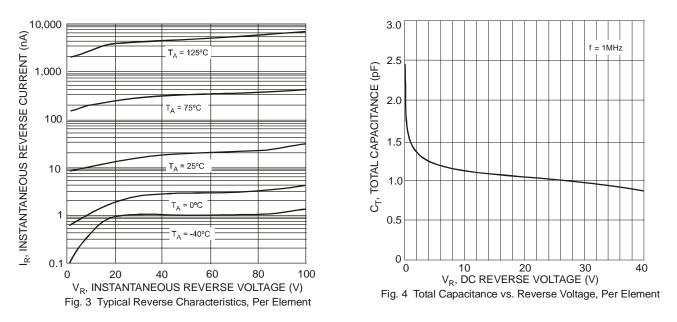
s: 5. Device mounted on FR-5 PCB 1.0 x 0.75 x 0.062 inch pad layout as shown on Diodes Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.

6. Short duration pulse test used to minimize self-heating effect.

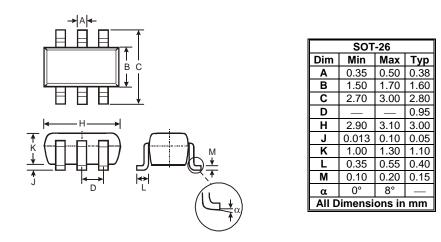




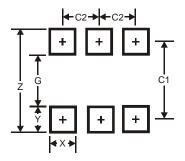




Package Outline Dimensions



Suggested Pad Layout



| Dimensions | Value (in mm) |
|------------|---------------|
| Z | 3.20 |
| G | 1.60 |
| Х | 0.55 |
| Y | 0.80 |
| C1 | 2.40 |
| C2 | 0.95 |



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